

REVISION				
REV	DESCRIPTION	DCN	DATE	BY/APPD
1	Add 50 ohm data to fab.		4-21-11	KAK

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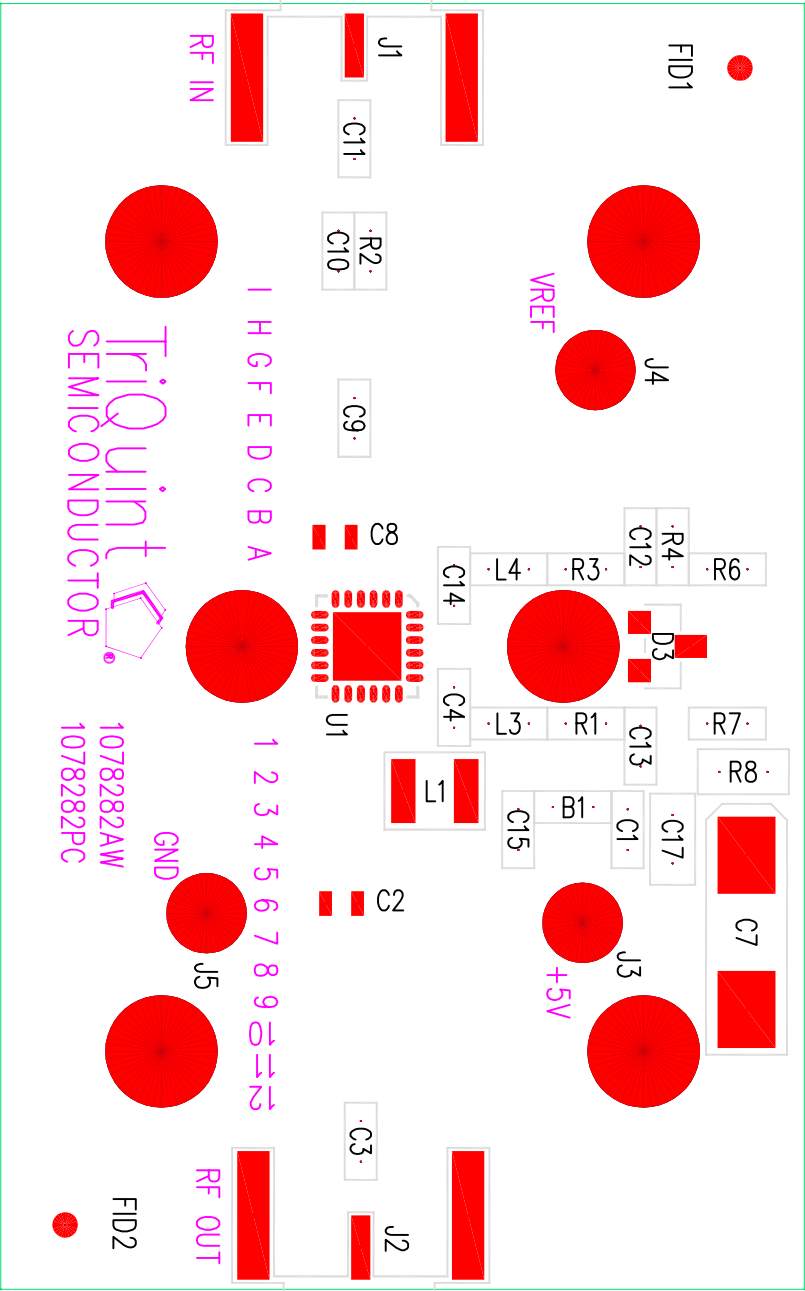
3

2

1

NOTES UNLESS OTHERWISE SPECIFIED:

1. ASSEMBLE IAW J-STD-001 CURRENT REVISION. THE ASSEMBLY IS TO MEET THE INSPECTION CRITERIA OF IPC-A-610, CLASS 2, CURRENT REVISION.
2. REFERENCE DOCUMENTS:
SCHEMATIC DIAGRAM: 1078282SD.
BILL OF MATERIAL: 1078282-001, CURRENT REV.
3. THIS ASSEMBLY CONTAINS ELECTROSTATIC SENSITIVE DEVICES; HANDLE IAW MIL-STD-1686, CLASS 2.
4. SOLDER PASTE THICKNESS TO BE .006 ±.002.
5. CONVECTION HEATING ONLY IS TO BE USED DURING SOLDER REFLOW, NO IR.
6. BAG AND TAG INDIVIDUAL BOARD WITH APPROPRIATE PART NO. 455841-XXX, CURRENT REV LEVEL.
7. VIA'S ARE OMITTED FOR CLARITY.
8. PADS OF SMALL CHIP RESISTORS AND CAPACITORS ARE OMITTED FOR CLARITY.
9. AQUEOUS CLEANING IS REQUIRED.
10. NO-LOAD PARTS: ALL COMPONENTS WITH TRIQUINT PART NO. 445930-001. SEE BOM.
11. EDIT GERBER FILE TO OMIT SOLDER STENCIL FOR THE FOLLOWING COMPONENTS: C2, C8.
12. USE SOLDER PASTE 863000-864.



COMPONENT SIDE

TRIQUINT SEMICONDUCTOR PROPRIETARY INFORMATION

QTY	PIER DASH	NO	ITEM NO	PART OR IDENT NO	CAGE CODE	NOMENCLATURE OR DESCRIPTION	SPEC./STD
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PARTS LIST OR MATERIAL

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES.

XX DEC ± .02
XXX DEC ± .005
TOLERANCES UNLESS SPECIFIED
ANGLES ± 0° 30'

MATERIAL:

OR K. KEISEN

8-4-10

OR K. KEISEN

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A

B

1078282

C

D

DSIZE 7/8/08

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